Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Cancelled)

2. (Currently Amended) A blade server module comprising:

a housing assembly;

a printed circuit board disposed within the housing assembly and mounted ~~in a free-floating relationship~~ for limited free-floating movement within the housing assembly, in a vertical direction thereto;

a processor mounted on the printed circuit board;

a heat sink surface disposed in the housing assembly in close proximity to the processor; and,

at least one compliant compression element disposed within the housing assembly and being preloaded for resiliently loading the processor into continuous thermal engagement with the heat sink surface, and compensate for displacements of the printed circuit board and expansion of the compliant compression element by heat.

3. (Original) The module of claim 2 wherein the one compliant compression element comprises a thin and flexibly resilient pad that assists in retaining the loading despite changes in temperature.

4. (Original) The module of claim 3 wherein the thin and flexibly resilient pad is an open cellular material.

5. (Original) The module of claim 4 wherein the open cellular foam material is BF-1000 silicone.

6. (Original) The module of claim 2 further comprising a thermal interface paste between the processor and the heat sink surface.

7. (Original) The module of claim 4 further comprising the resilient pad being in direct contact with a surface of the printed circuit board which is opposing a surface carrying the processor.

8. (Cancelled)

9. (Cancelled)

10. (Cancelled)

11. (Cancelled)

12. (Currently Amended) A blade server system comprising:

a blade server console constructed for pluggable reception of corresponding ones of blade server modules; and,

one or more blade server modules, each of which is for plugging into the blade server console;

each one of the blade server modules comprising a first sidewall portion and a second sidewall portion;

each one of the blade server modules further comprising ~~comprises~~: a ~~free-floating~~ printed circuit board disposed between the first sidewall portion and the second sidewall portion, ~~therein~~ the printed circuit board mounted for limited free-floating movement within each one of the blade server modules, in a vertical direction relative to the sidewall portions of each one of the blade server modules; a processor mounted on the printed circuit board; a heat sink surface in close proximity to the processor; and, at least a compliant compression element preloaded to resiliently urge the printed circuit board into

continuous thermal engagement with the heat sink surface with a predefined retention force.

13. (Original) The system of claim 12 wherein the compliant compression element includes a thin and flexibly resilient pad that retains loading characteristics despite changes in temperature.

14. (Original) The system of claim 13 wherein the compliant compression element is an open cell foam material.

15. (Original) The system of claim 14 further comprises a thermal interface paste between the processor and the heat sink surface.